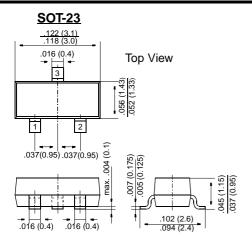
BCV27

Darlington Transistor

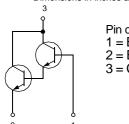


FEATURES

- ♦ High collector current
- ♦ High current gain
- NPN Silicon Planar Darlington Transistor for general NF applications
- As complementary type, the PNP transistor BCV26 is recommended.



Dimensions in inches and (millimeters)



Pin configuration

1 = Base

2 = Emitter 3 = Collector

MECHANICAL DATA

Case: SOT-23 Plastic Package **Weight:** approx. 0.008 g

Marking

FF

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Value	Unit	
Collector-Emitter Voltage	V _{CEO}	30	V	
Collector-Base Voltage	V _{CBO}	40	V	
Emitter-Base Voltage	V _{EBO}	10	V	
Collector Current	Ic	300	mA	
Peak Collector Current	I _{CM}	800	mA	
Base Current	I _B	100	mA	
Power Dissipation at T _{SB} = 50 °C	P _{tot}	3001)	mW	
Junction Temperature	Tj	150	°C	
Storage Temperature Range	T _S	-65 to +150	°C	
1) Device on fiberglass substrate, see layout		1	1	

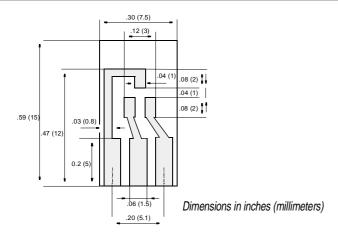


ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Min.	Тур.	Max.	Unit
Collector-Base Cutoff Current at V _{CBO} = 30 V	I _{CBO}	_	-	0.1	μΑ
Emitter-Base Cutoff Current at V _{EB} = 10 V	I _{EBO}	-	-	0.1	μА
Collector-Emitter Breakdown Voltage at I _C = 10 mA	V _{(BR)CEO}	30	-	_	V
Collector-Base Breakdown Voltage at $I_C = 10 \mu A$	V _(BR) CBO	40	-	_	V
Emitter-Base Breakdown Voltage at I _E = 100 nA	V _{(BR)EBO}	10	-	_	V
DC Current Gain at $V_{CE} = 5 \text{ V}$, $I_C = 1 \text{ mA}$ at $V_{CE} = 5 \text{ V}$, $I_C = 10 \text{ mA}$ at $V_{CE} = 5 \text{ V}$, $I_C = 100 \text{ mA}$	h _{FE} h _{FE}	4000 10000 20000	- - -	- - -	- - -
Collector-Emitter Saturation Voltage at $I_C = 100 \text{ mA}$, $I_B = 0.1 \text{ mA}$	VCEsat	_	_	1.0	V
Base-Emitter Saturation Voltage at $I_C = 100 \text{ mA}$, $I_B = 0.1 \text{ mA}$	V _{BEsat}	_	-	1.5	V
Gain-Bandwidth Product at V _{CE} = 5 V, I _C = 30 mA, f = 100 MHz	f _T	_	220	_	MHz
Collector-Base Capacitance at $V_{CB} = 30 \text{ V}$, $I_E = 0$, $f = 1 \text{ MHz}$	ССВО	_	3.5	_	pF
Thermal Resistance Junction to Ambient Air	R _{thJA}	_	_	430 ¹⁾	K/W

¹⁾ Device on fiberglass substrate, see layout below



Layout for R_{thJA} test
Thickness: Fiberglass 0.059 in (1.5 mm)
Copper leads 0.012 in (0.3 mm)

